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| | <h1>Tentative</h1> | DMA364A6 | |
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DMA364A6

Silicon PNP epitaxial planar type (Tr1)

Silicon PNP epitaxial planar type (Tr2)

For digital circuits

Marking Symbol : N1

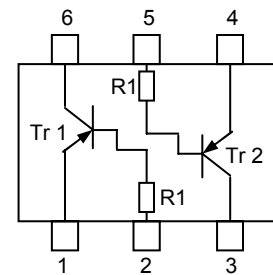
Package Code : SSSMini6-F2-B

Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

| Parameter | | Symbol | Rating | Unit |
|-----------|---------------------------------------|--------|-------------|------------------|
| Tr1 | Collector-base voltage (Emitter open) | VCBO | -50 | V |
| | Collector-emitter voltage (Base open) | VCEO | -50 | V |
| Tr2 | Collector current | IC | -80 | mA |
| Overall | Total power dissipation *1 | PT | 125 | mW |
| | Junction temperature | Tj | 150 | $^\circ\text{C}$ |
| | Storage temperature | Tstg | -55 to +150 | $^\circ\text{C}$ |

Note: 1. *1 Measuring on substrate at 17 mm × 10 mm × 1 mm

Internal Connection



| | | | |
|------------------|----|-----|------------|
| Resistance value | R1 | 4.7 | k Ω |
|------------------|----|-----|------------|

Pin name

| | |
|-------------------|-------------------|
| 1. Emitter(Tr1) | 4. Emitter(Tr2) |
| 2. Base(Tr1) | 5. Base(Tr2) |
| 3. Collector(Tr2) | 6. Collector(Tr1) |

Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Tr1,Tr2

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|----------|-------------------------------------|------|-----|-------|---------------|
| Collector-base voltage (Emitter open) | VCBO | IC = -10 μA , IE = 0 | -50 | | | V |
| Collector-emitter voltage (Base open) | VCEO | IC = -2 mA, IB = 0 | -50 | | | V |
| Collector-base cutoff current (Emitter open) | ICBO | VCB = -50 V, IE = 0 | | | -0.1 | μA |
| Collector-emitter cutoff current (Base open) | ICEO | VCE = -50 V, IB = 0 | | | -0.5 | μA |
| Emitter-base cutoff current (Collector open) | IEBO | VEB = -6 V, IC = 0 | | | -0.01 | mA |
| Forward current transfer ratio | hFE | VCE = -10 V, IC = -5 mA | 160 | | 460 | - |
| Collector-emitter saturation voltage | VCE(sat) | IC = -10 mA, IB = -0.5 mA | | | -0.25 | V |
| Input voltage | Vi(on) | VCE = -0.2 V, IC = -5 mA | -1.0 | | | V |
| | Vi(off) | VCE = -5 V, IC = -100 μA | | | -0.4 | |
| Input resistance | R1 | | -30% | 4.7 | +30% | k Ω |

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. *1 Pulse measurement

Packing

Embossed type (Thermo-compression sealing) R specification : 10 000 pcs / reel

| | | |
|-----------|-----------|--|
| 2010.3.10 | 2010.9.21 | |
| Prepared | Revised | |

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